



EKC CuSolve™ Technology

Copper compatible cleaning products formulated specifically for advanced designs integrating copper. These products remove photoresist and copper containing residues in the presence of exposed copper and low-k materials.

EKC500™ Cu Series

EKC505™ Cu

Solvent based solution designed for complete removal of photoresist in the presence of low-k dielectric and exposed copper without damage. Demonstrates excellent compatibility with copper structures. Very effective in maintaining the structural integrity of vias and copper containing dual damascene structures.

EKC510™ Cu

An aqueous/organic formulation which removes plasma hardened DUV photoresist on advanced copper interconnects. This product provides an effective low-cost process with improved yields compared to alternative dual hard-mask integration schemes.

EKC525™ Cu

An advanced formulation designed for use at the cutting edge of advanced interconnect, damascene and dual damascene architectures where copper is employed as the interconnect metal. This product completely removes copper residues created at the end of dielectric etch. Used under mild conditions for relatively short times, this product is completely benign towards copper.

EKC's applications engineering staff will provide support for selecting the appropriate product. Development and sustaining engineering is provided for existing and new processes as EKC's applications engineers are available to work at your facility or do additional wafer testing at the EKC applications lab.

U.S. and Foreign Patents Pending

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DuPont Electronic Technologies

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